(0,635mm) .025"

QFS-078-04.25-L-D-PC4 QFS-052-04.25-L-D-RF1

QFS-PC, QFS-RF SERIES

## HIGH SPEED COMBO RF & POWER

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?QFS-PC or www.samtec.com?QFS-RF

Insulator Material: Liquid Crystal Polymer Contact & Ground Plane Material: Phosphor Bronze Plating:

Au over 50μ" (1,27μm) Ni (Tin on Ground Plane Tail) **Current Rating:** 

Signal Contact: 1.8A @ 80°C Power Contact: 4.1A @ 80°C Ground Plane: 8.9A @ 80°C Voltage Rating: 300 VAC mated with QMS Operating Temp: -55°C to +125°C RoHS Compliant:

## **Processing:**

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

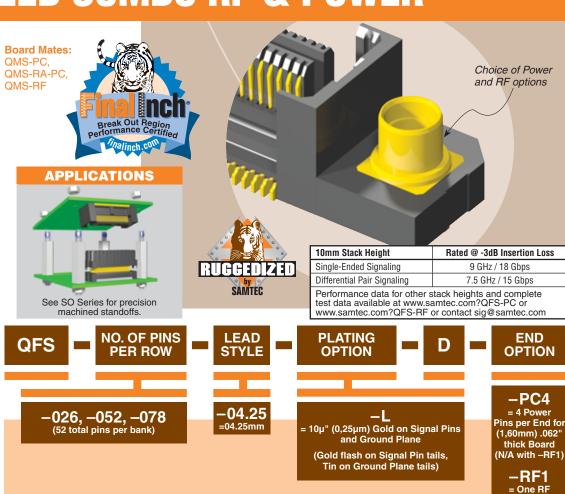
SMT Lead Coplanarity: (0,10mm) .004" max (026-078) Board Stacking:

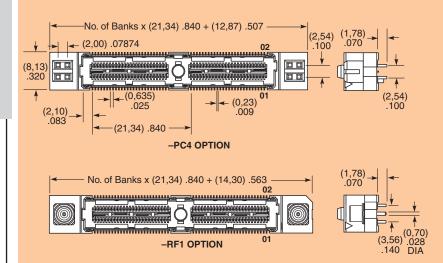
For applications requiring more than two connectors per board, contact ipg@samtec.com

## APPLICATION SPECIFIC OPTION

- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1,60mm) .062" thick Board
- 4 or 8 Power Pins/End for (2,36mm) .093" thick Board
- 2 RF Connectors/End
- Hot Pluggable

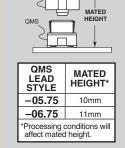
Call Samtec.





APPLICATION

Jack per End (N/A with -PC4)



Note: Some lengths. styles and options are non-standard, non-returnable.